

## Silicon Carbide PiN Diode Chip

### Features

- 10 kV blocking
- 250 °C operating temperature
- Fast turn off characteristics
- Soft reverse recovery characteristics
- Ultra-Fast high temperature switching



### Advantages

- Industry's lowest conduction losses
- Reduced stacking
- Reduced system complexity/Increased reliability

### Applications

- Voltage Multiplier
- Ignition/Trigger Circuits
- Oil/Downhole
- Lighting
- Defense

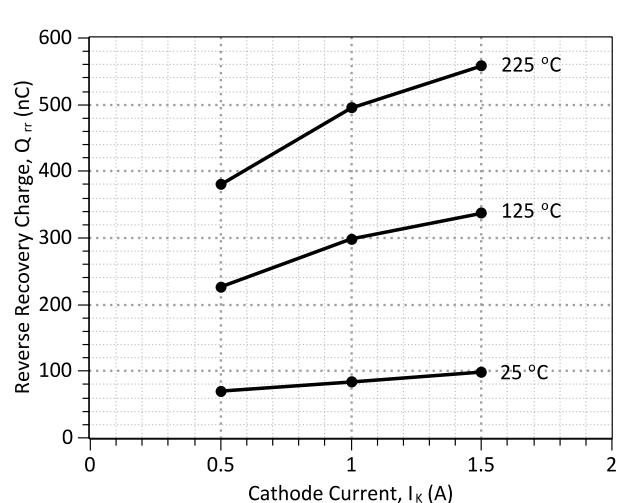
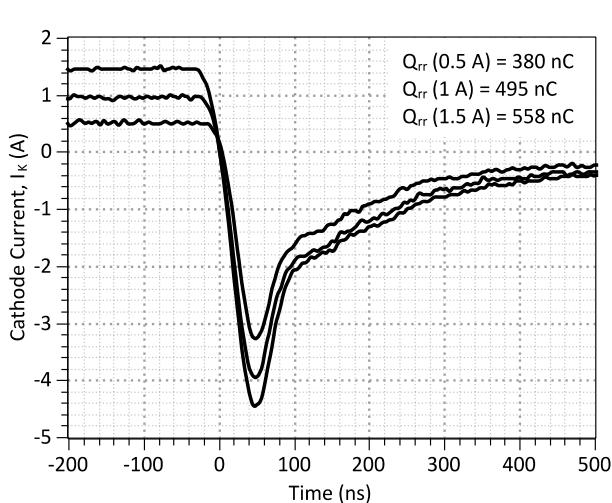
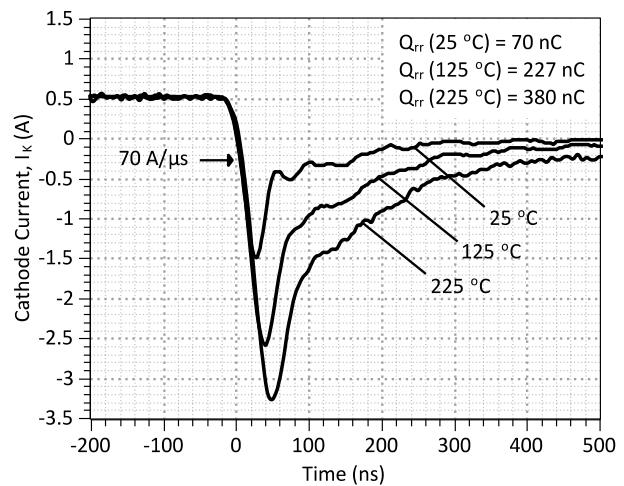
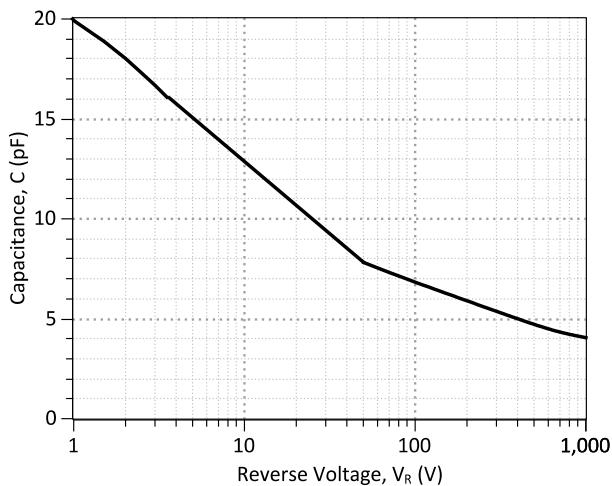
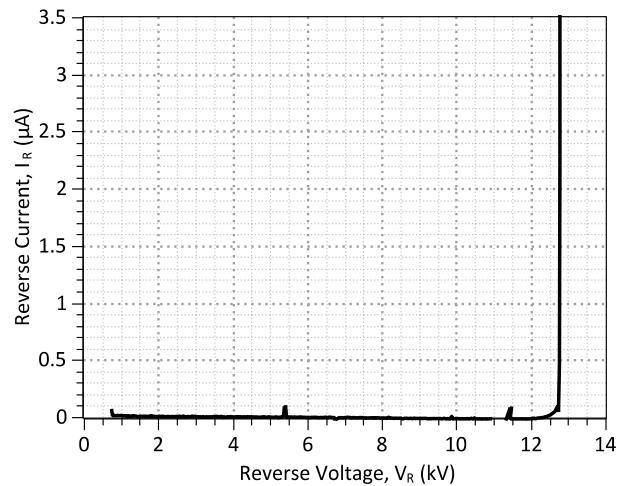
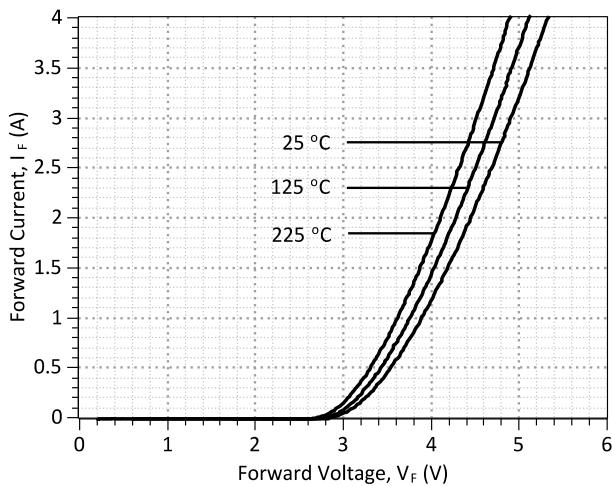
### Maximum Ratings at $T_j = 250^\circ\text{C}$ , unless otherwise specified

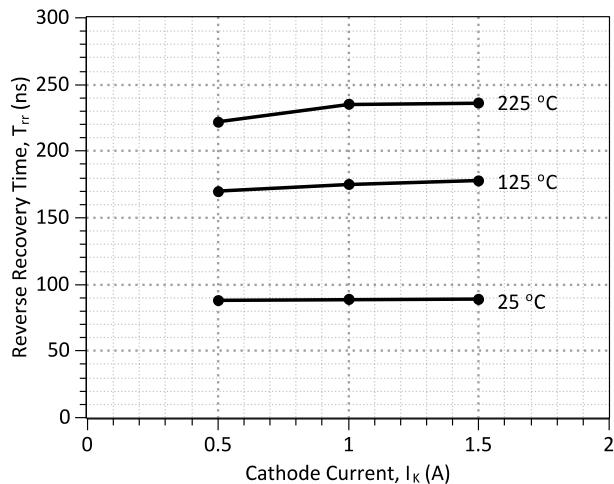
Parameter	Symbol	Conditions	Values	Unit
Repetitive peak reverse voltage	$V_{RRM}$		10	kV
Continuous forward current	$I_F$	$T_C \leq 150^\circ\text{C}$	2	A
RMS forward current	$I_{F(RMS)}$	$T_C \leq 150^\circ\text{C}$	1	A
Operating and storage temperature	$T_j, T_{stg}$		-55 to 250	°C

### Electrical Characteristics at $T_j = 250^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Diode forward voltage	$V_F$	$I_F = 2 \text{ A}, T_j = 25^\circ\text{C}$	4.4	4.8	4.5	V
		$I_F = 2 \text{ A}, T_j = 225^\circ\text{C}$	4.1	4.5	4.1	
Reverse current	$I_R$	$V_R = 10 \text{ kV}, T_j = 25^\circ\text{C}$	0.1	3	50	$\mu\text{A}$
		$V_R = 10 \text{ kV}, T_j = 225^\circ\text{C}$				
Total reverse recovery charge	$Q_{rr}$	$I_F \leq I_{F,MAX}$	$V_R = 1000 \text{ V}$	558		nC
		$dl_F/dt = 70 \text{ A}/\mu\text{s}$	$I_F = 1.5 \text{ A}$			
Switching time	$t_s$	$T_j = 225^\circ\text{C}$	$V_R = 1000 \text{ V}$	< 236		ns
			$I_F = 1.5 \text{ A}$			
Total capacitance	C	$V_R = 1 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ\text{C}$	20			pF
		$V_R = 400 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ\text{C}$	5			
		$V_R = 1000 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ\text{C}$	4			
Total capacitive charge	$Q_C$	$V_R = 1000 \text{ V}, f = 1 \text{ MHz}, T_j = 25^\circ\text{C}$	5.34			nC

\*For chip size and metallization, please refer to the mechanical datasheet (must have a non-disclosure agreement with GeneSiC Semiconductor).




**Figure 7: Reverse Recovery Time vs Cathode Current**

Revision History			
Date	Revision	Comments	Supersedes
2012/08/15	0	Initial release	

## Published by

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